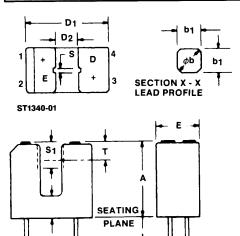


H22A1/2/3

PACKAGE DIMENSIONS

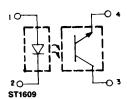


SYMBOL	MILLIMETERS		INC	NOTES	
STWIDOL	MIN.	MAX.	MIN.	MAX.	IIIO I LO
Α	10.7	11.0	.422	.433	
A,	3.0	3.2	.119	.125	
₩b	.600	.750	.024	.030	2
b,	.50 N	IOM.	.020 l	NOM.	2
D,	11.6	12.0	.457	.472	
D ₂	3.0	3.3	.119	.129	
e,	6.9	7.5	.272	.295	
e₂	2.3	2.8	.091	.110	
E	6.15	6.35	.243	.249	
L	8.00		.315		
S	.85	1.0	.034	.039	
S ₁	3.45	3.75	.136	.147	
Т	2.61	IOM.	.103	NOM.	3

NOTES:

- 1. INCH DIMENSIONS ARE DERIVED FROM MILLIMETERS.
- 2. FOUR LEADS. LEAD CROSS SECTION IS CONTROLLED BETWEEN 1.27mm (.050") FROM SEATING PLANE AND THE END OF THE LEADS.
- 3. THE SENSING AREA IS DEFINED BY THE "S" DIMENSION AND BY DIMENSION "T" $\pm 0.75 \text{mm}$ ($\pm .030 \text{ INCH}$).

PACKAGE OUTLINE



ST1340-02

DESCRIPTION

The H22A Slotted Optical Switch is a gallium arsenide light emitting diode coupled to a silicon photodarlington in a plastic housing. The packaging system is designed to optimize the mechanical resolution, coupling efficiency, ambient light rejection, cost and reliability. The gap in the housing provides a means of interrupting the signal with an opaque material, switching the output from an "ON" to an "OFF" state.

FEATURES

- Opaque housing
- Low cost
- .035" apertures
- High I_{C(ON)}



Operating Temperature	55°C to +100°C
- p	−55°C to +100°C
Soldering:	240°C for E 222 845
Lead Temperature (Iron) Lead Temperature (Flow)	
INPUT DIODE	
Continuous Forward Current	
Reverse Voltage	
Power Dissipation	100 mW ^c
OUTPUT TRANSISTOR	
Collector-Emitter Voltage	30 Volts
Emitter-Collector Voltage	

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
INPUT DIODE						
Forward Voltage	$V_{\scriptscriptstyle F}$			1.7	V	$I_F = 60 \text{ mA}$
Reverse Breakdown Voltage	V _R	6.0			٧	$I_R = 10\mu A$
Reverse Leakage Current	l _R	_		1.0	μΑ	V _R = 3 V
OUTPUT TRANSISTOR			74.			
Emitter-Collector Breakdown	BV_{eco}	6.0		_	V	$I_{\rm E}=100~\mu{\rm A},{\rm Ee}=0$
Collector-Emitter Breakdown	BV _{CEO}	30	_	_	V	$I_c = 1$ mA, Ee = 0
Collector-Emitter Leakage	I _{CEO}	_		100	nA	V _{CE} = 25 V, Ee = 0
COUPLED						,
On-State Collector Current	I _{C(ON)}		See page 3.		mA	
Saturation Voltage	V _{CE(SAT)}		See page 3.		٧	
Turn-On Time	t _{on}		See page 3.		μS	
Turn-Off Time	t _{off}		See page 3.	· ·	μS	

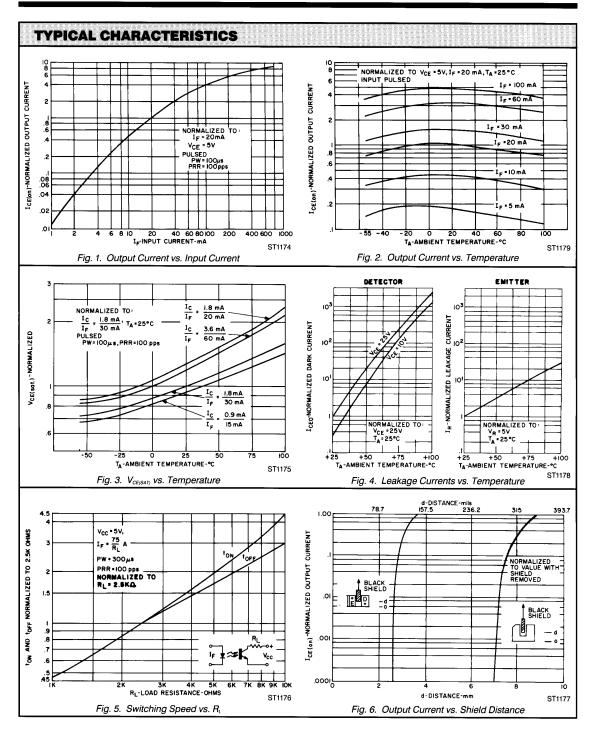
NOTES

- Derate power dissipation linearly 1.33 mW/°C above 25°C.
 Derate power dissipation linearly 2.00 mW/°C above 25°C.
 RMA flux is recommended.
- Methanol or Isopropyl alcohols are recommended as cleaning agents.
 Soldering iron tip 1/16" (1.6 mm) from housing.



PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
ON-STATE COLLECTOR	CURRENT		· .		···	· · · · · · · · · · · · · · · · · · ·
H22A1	$I_{C(ON)}$	0.15	_	_	mA	$I_F = 5mA$, $V_{CE} = 5V$
H22A2	I _{C(ON)}	0.30	_	_	mA	$I_F = 5mA$, $V_{CE} = 5V$
H22A3	I _{C(ON)}	0.60			mA	$I_F = 5$ mA, $V_{CE} = 5$ V
H22A1	I _{C(ON)}	1.0		_	mA	I _F = 20mA, V _{CE} = 5V
H22A2	I _{C(ON)}	2.0	_	_	mA	$I_F = 20 \text{mA}, V_{CE} = 5 \text{V}$
H22A3	I _{C(ON)}	4.0			mA	$I_F = 20 \text{mA}, V_{CE} = 5 \text{V}$
H22A1	I _{C(ON)}	1.9		_	mA	$I_F = 30$ mA, $V_{CE} = 5$ V
H22A2	I _{C(ON)}	3.0	_		mA	$I_F = 30 \text{mA}, V_{CE} = 5 \text{V}$
H22A3	(C(ON)	5.5			mA	$I_F = 30 \text{mA}, V_{CE} = 5 \text{V}$
SATURATION VOLTAGE	<u> </u>		.			
H22A2	$V_{CE(SAT)}$	_	_	0.40	٧	$I_F = 20 \text{mA}, I_C = 1.8 \text{mA}$
H22A3	$V_{\text{CE(SAT)}}$		_	0.40	٧	$I_F = 20$ mA, $I_C = 1.8$ mA
H22A1	$V_{CE(SAT)}$			0.40	. V	I _F = 30mA, I _C = 1.8mA
Turn-On Time	t _{on}		8		μS	$V_{cc} = 5V$, $I_F = 30$ mA, $R_L = 2.5$
Turn-Off Time	t _{off}	_	50		μS	$V_{cc} = 5V$, $I_{c} = 30$ mA, $B_{c} = 2.5$







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